

# HSD226

## Silicon Schottky Barrier Diode for High Speed Switching

REJ03G0603-0400

Rev.4.00

Feb 06, 2007

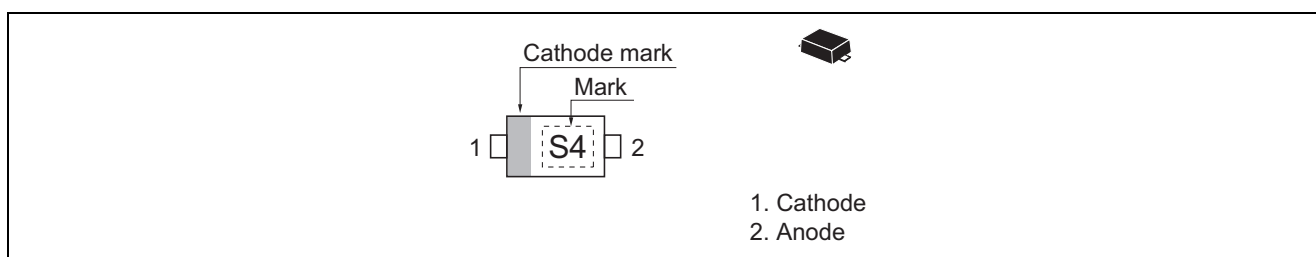
### Features

- Low Power consumption (Low reverse leak current) and high speed (Low capacitance).
- Lineup of Environmental friendly Halogen free type (HSD226-N)
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

### Ordering Information

| Type No.                        | Laser Mark | Package Name | Package Code |
|---------------------------------|------------|--------------|--------------|
| HSD226                          | S4         | SFP          | PUSF0002ZB-A |
| HSD226-N<br>(Halogen-free type) |            |              |              |

### Pin Arrangement



## Absolute Maximum Ratings

(Ta = 25°C)

| Item                                      | Symbol      | Value       | Unit |
|-------------------------------------------|-------------|-------------|------|
| Repetitive peak reverse voltage           | $V_{RRM}$   | 25          | V    |
| Non-Repetitive peak forward surge current | $I_{FSM}^*$ | 200         | mA   |
| Forward current                           | $I_F$       | 50          | mA   |
| Junction temperature                      | $T_j$       | 125         | °C   |
| Storage temperature                       | $T_{stg}$   | -55 to +125 | °C   |

Note: 10 ms sine wave 1 pulse

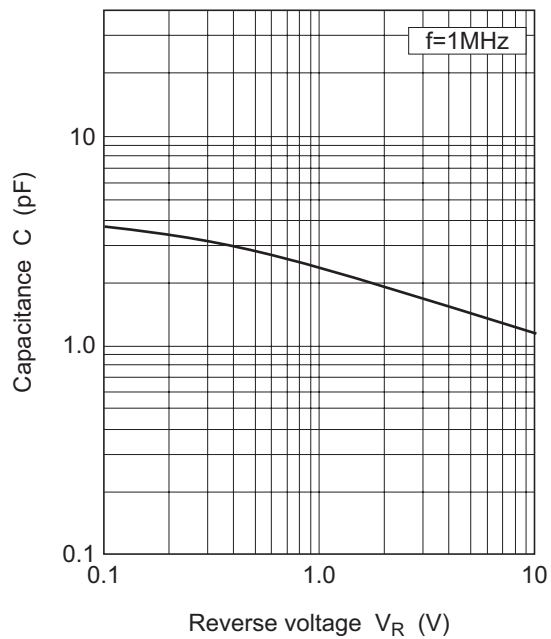
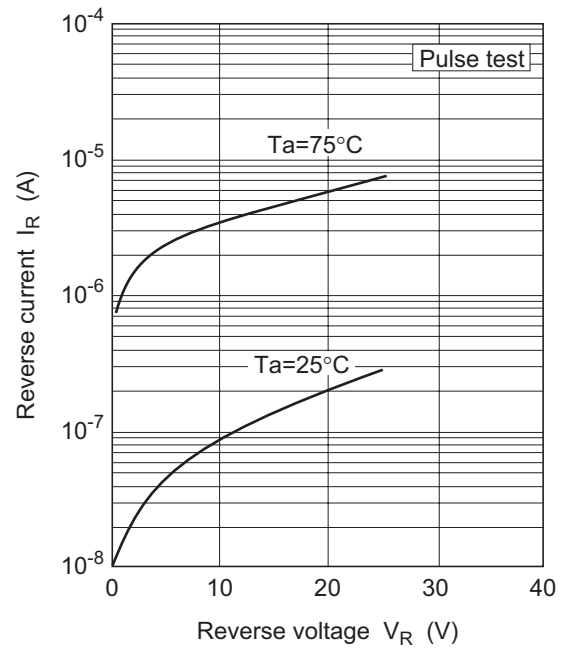
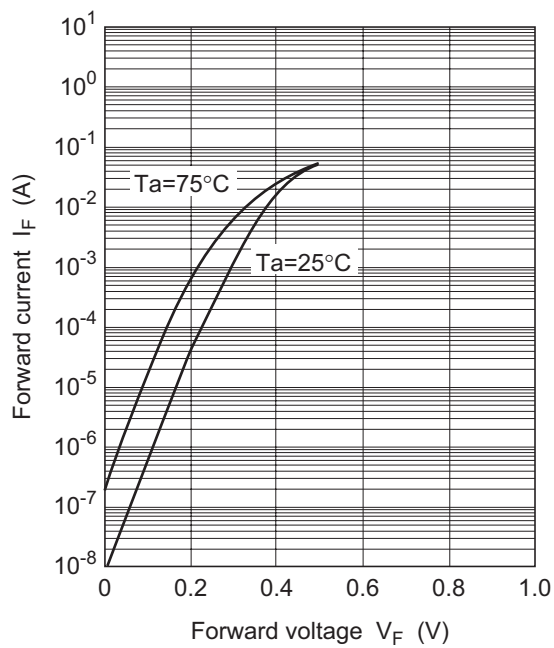
## Electrical Characteristics

(Ta = 25°C)

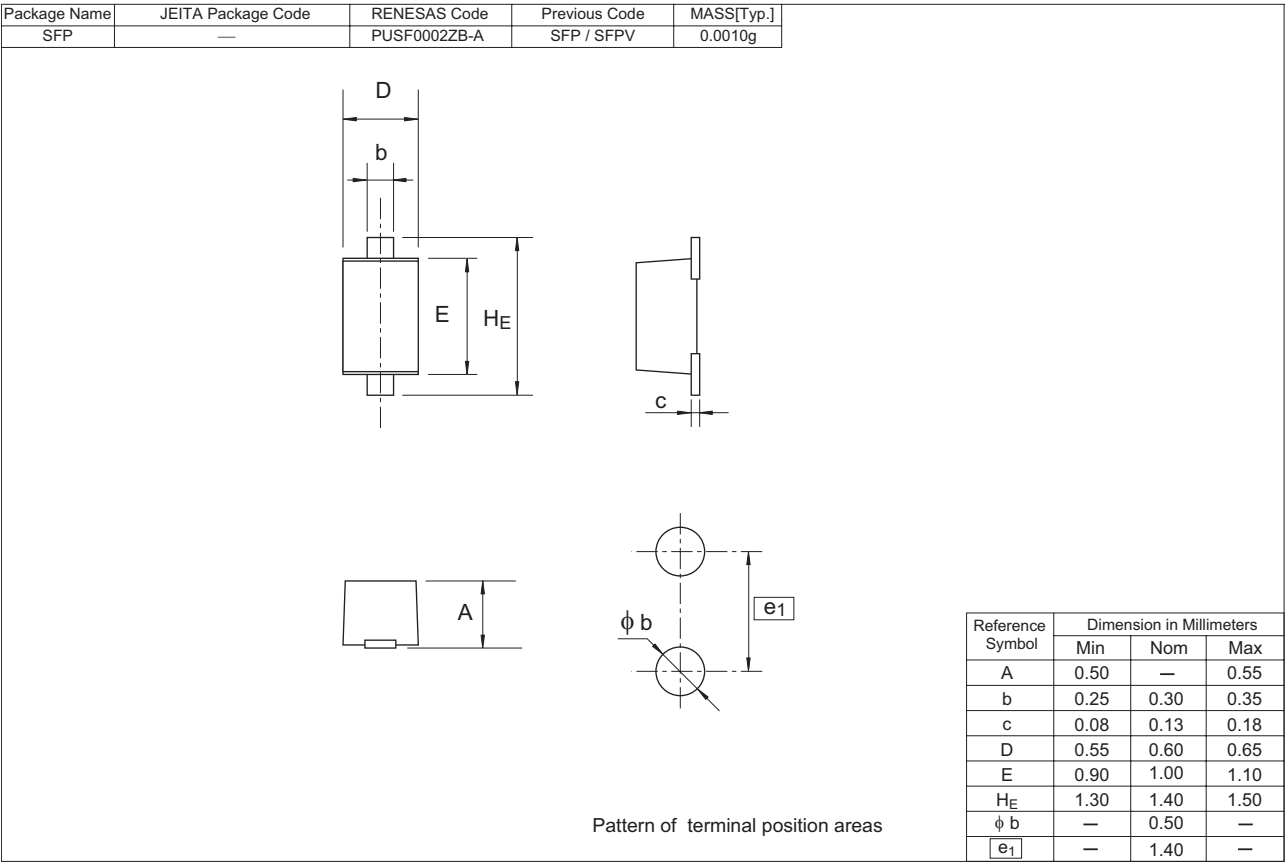
| Item            | Symbol   | Min | Typ | Max  | Unit | Test Condition                         |
|-----------------|----------|-----|-----|------|------|----------------------------------------|
| Forward voltage | $V_{F1}$ | —   | —   | 0.33 | V    | $I_F = 1 \text{ mA}$                   |
|                 | $V_{F2}$ | —   | —   | 0.38 | V    | $I_F = 5 \text{ mA}$                   |
| Reverse current | $I_R$    | —   | —   | 450  | nA   | $V_R = 20 \text{ V}$                   |
| Capacitance     | C        | —   | —   | 2.80 | pF   | $V_R = 1 \text{ V}, f = 1 \text{ MHz}$ |

Note: For SFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

## Main Characteristic



Package Dimensions



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